

## PCB Manufacturing Notes

### General Info

Board dimensions - 40mm x 70mm  
Number of layers - 2  
Smallest hole - 0.3mm  
Number of holes - Approx 165  
Minimum Track & Gap - 0.15mm  
RoHS/Lead Free - Yes  
Material - FR4 or equivalent

### Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
Layer 01 (Top)	0.5oz
Layer 02 (Bottom)	0.5oz

Finished board thickness to be 1.6mm ± 0.1mm

### Impedance Control

Not required.

### Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

### Finish

#### A.) Conductive finish

Plating to be immersion gold.

#### B.) Soldermask

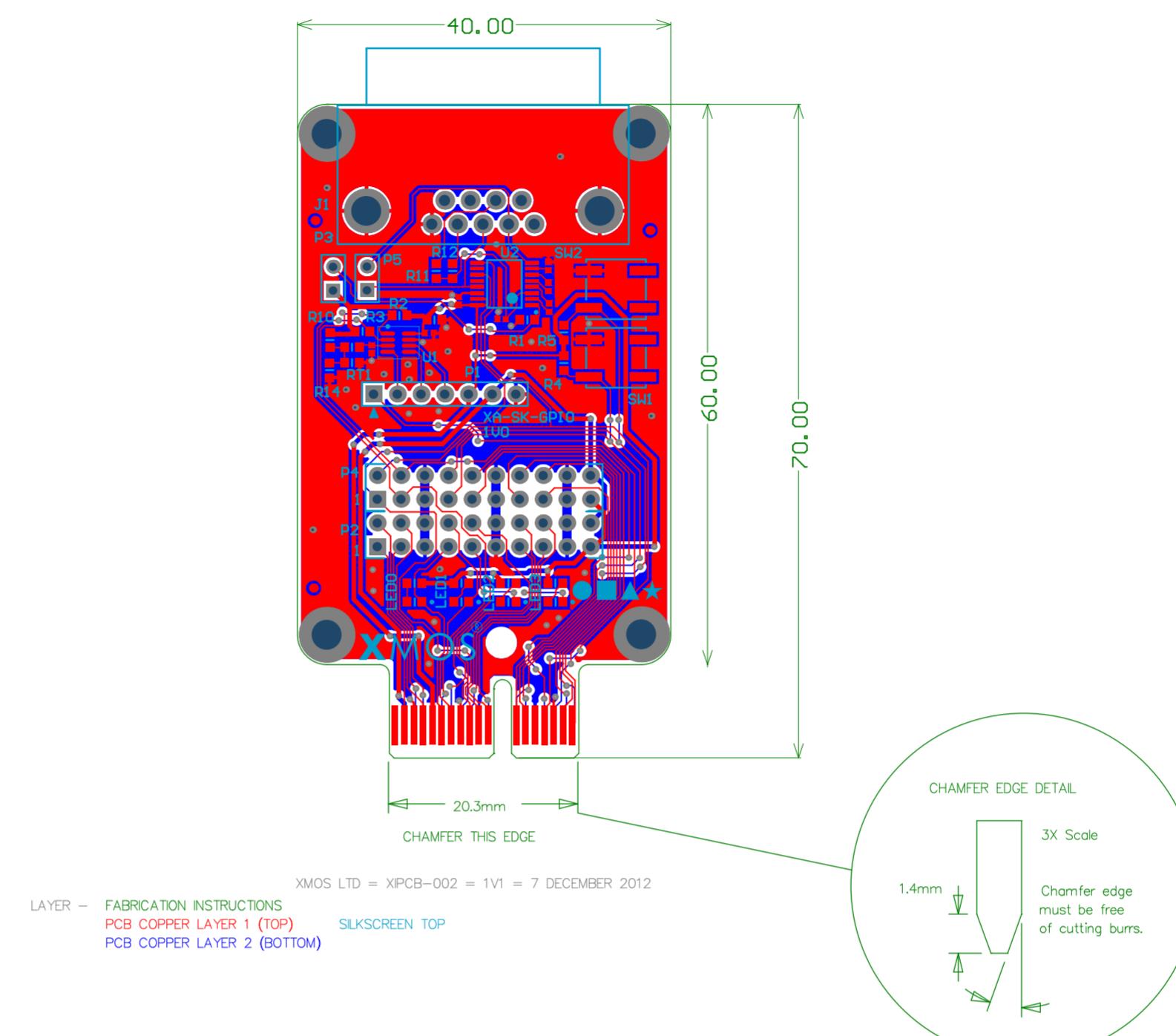
Liquid photo imageable soldermask (green). Pads have not been oversized.  
Supplier should oversize soldermask on pads to suit process.

#### C.) Silkscreen

Colour white. Supplier should remove any silkscreen which overhangs pads.

### Drill Data

Drill data is in Excellon format, metric (000.000), no zero suppression, absolute coordinates.  
Hole size is finished size.



XMOS®		
Project Name XIPCB-002 (XA-SK-GPIO)		
Sheet A4	Date 7 DECEMBER 2012	Revision 1V1
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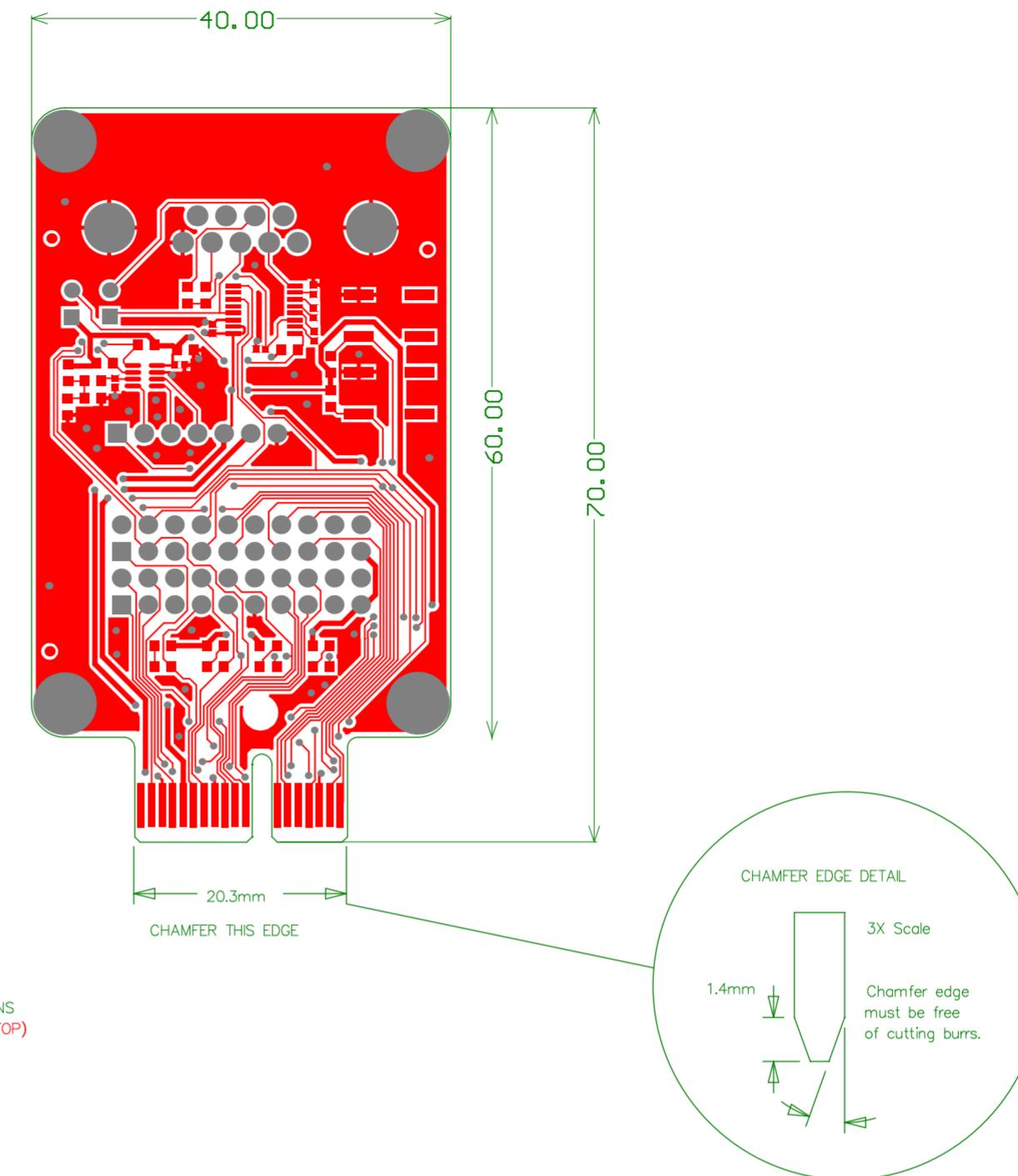
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A4	7 DECEMBER 2012	1V1
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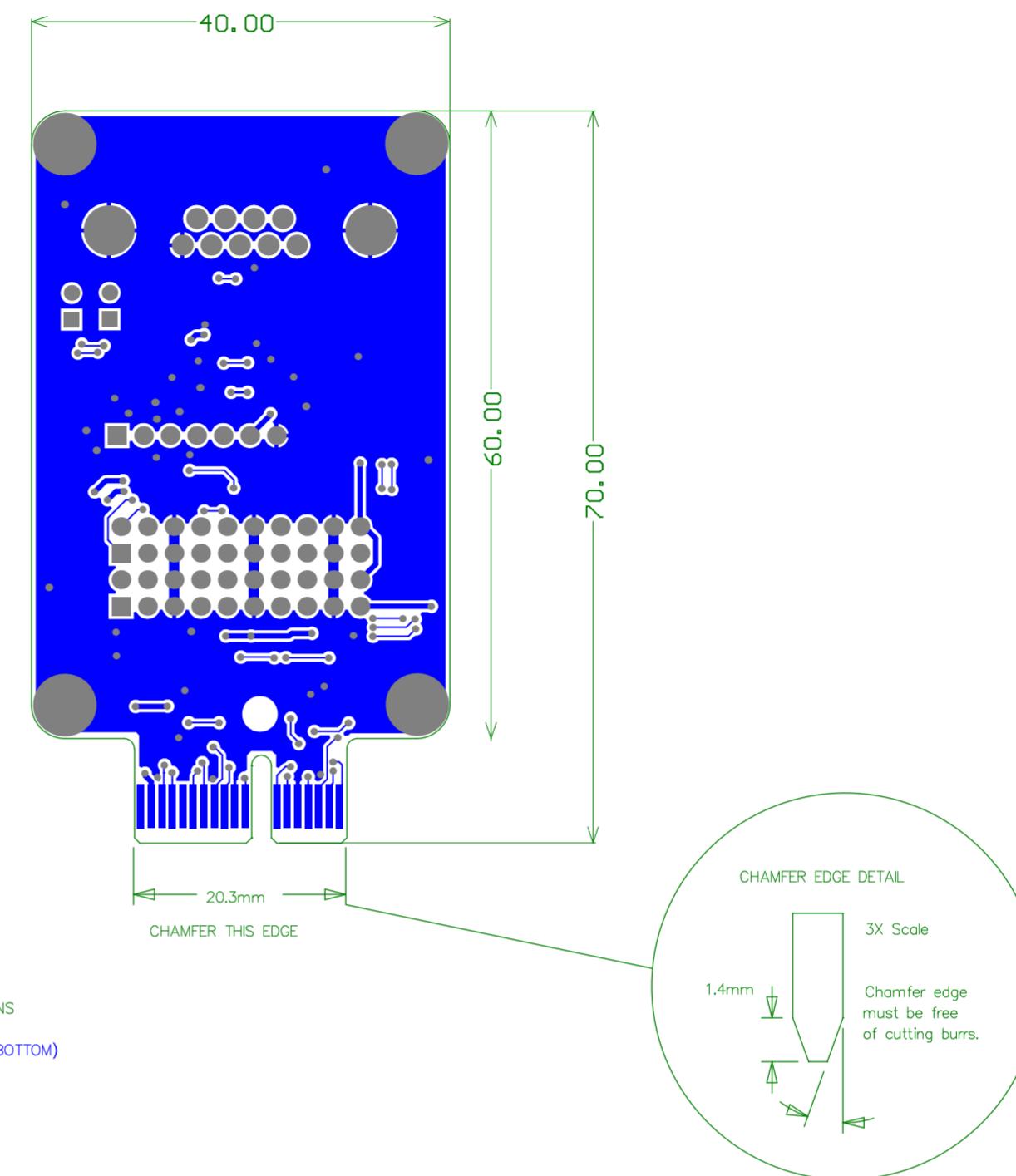
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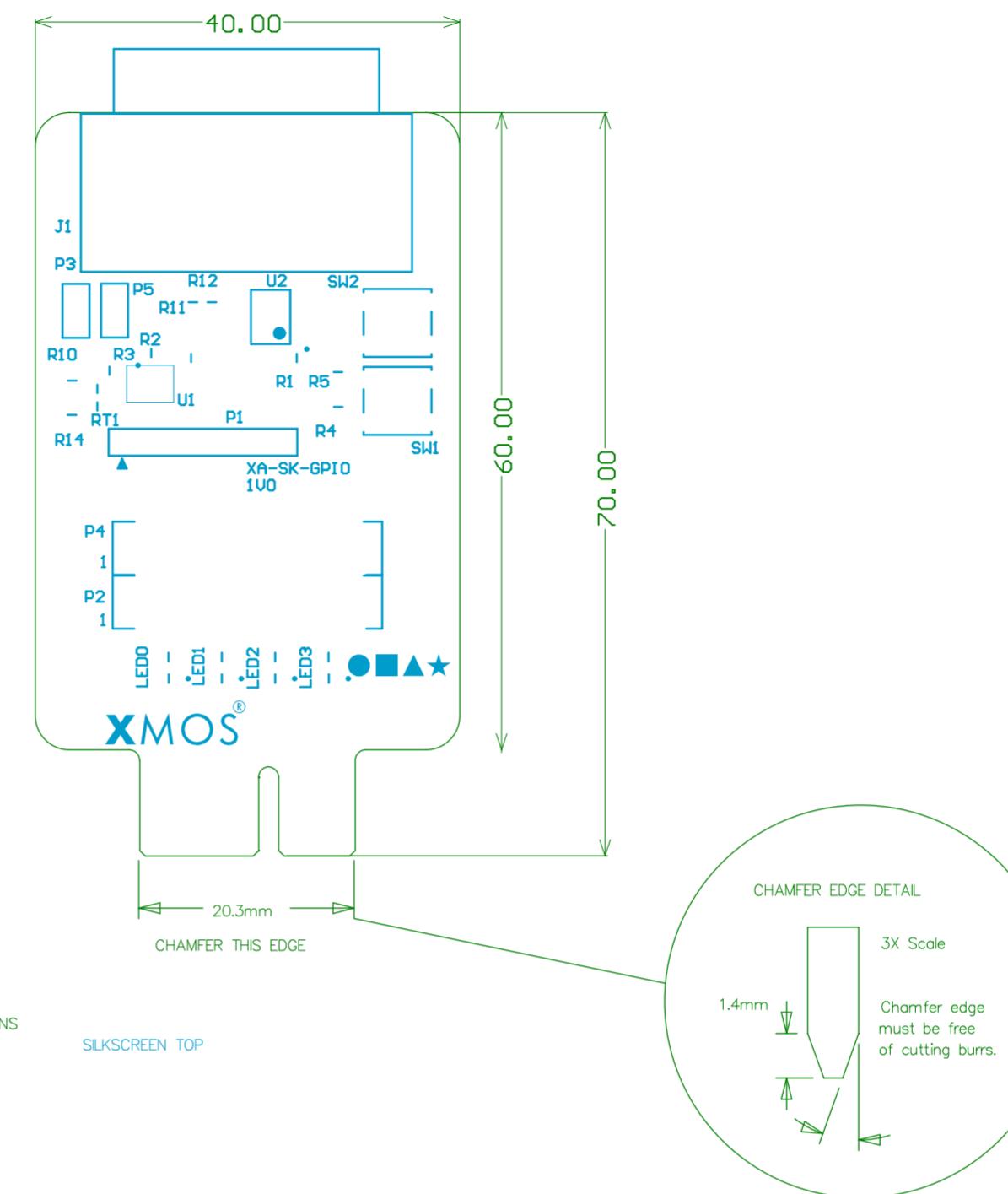
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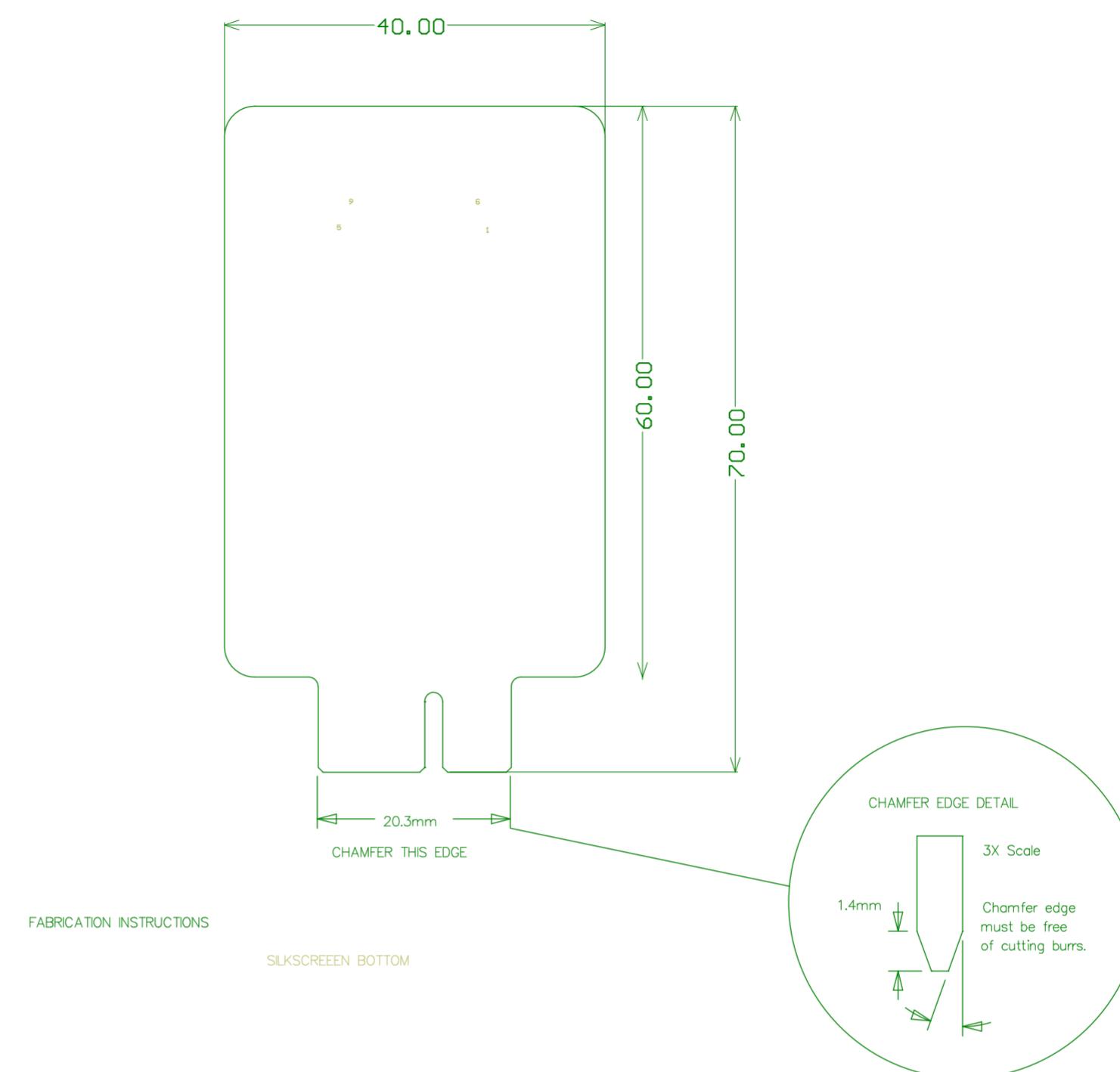
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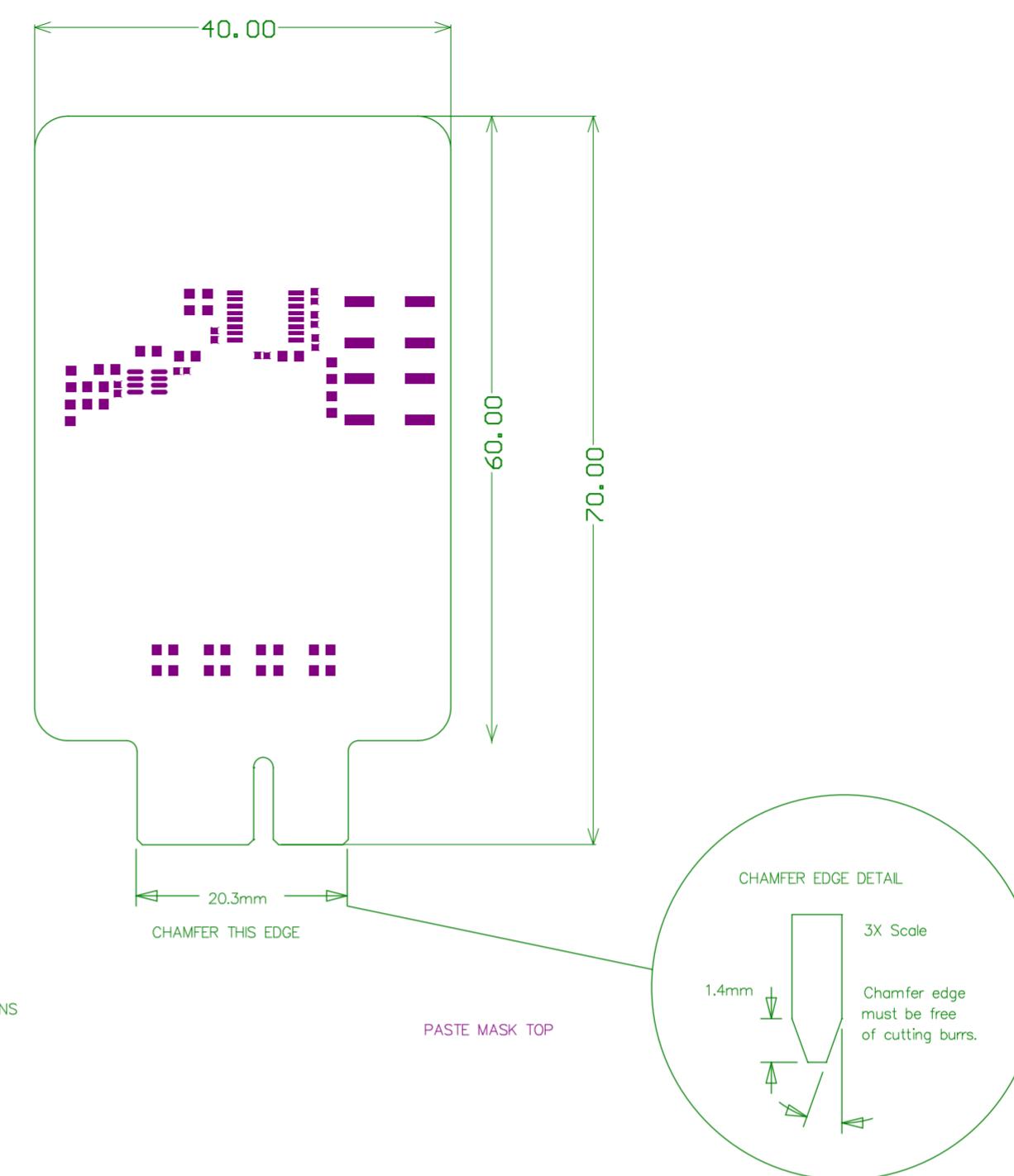
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FABRICATION INSTRUCTIONS

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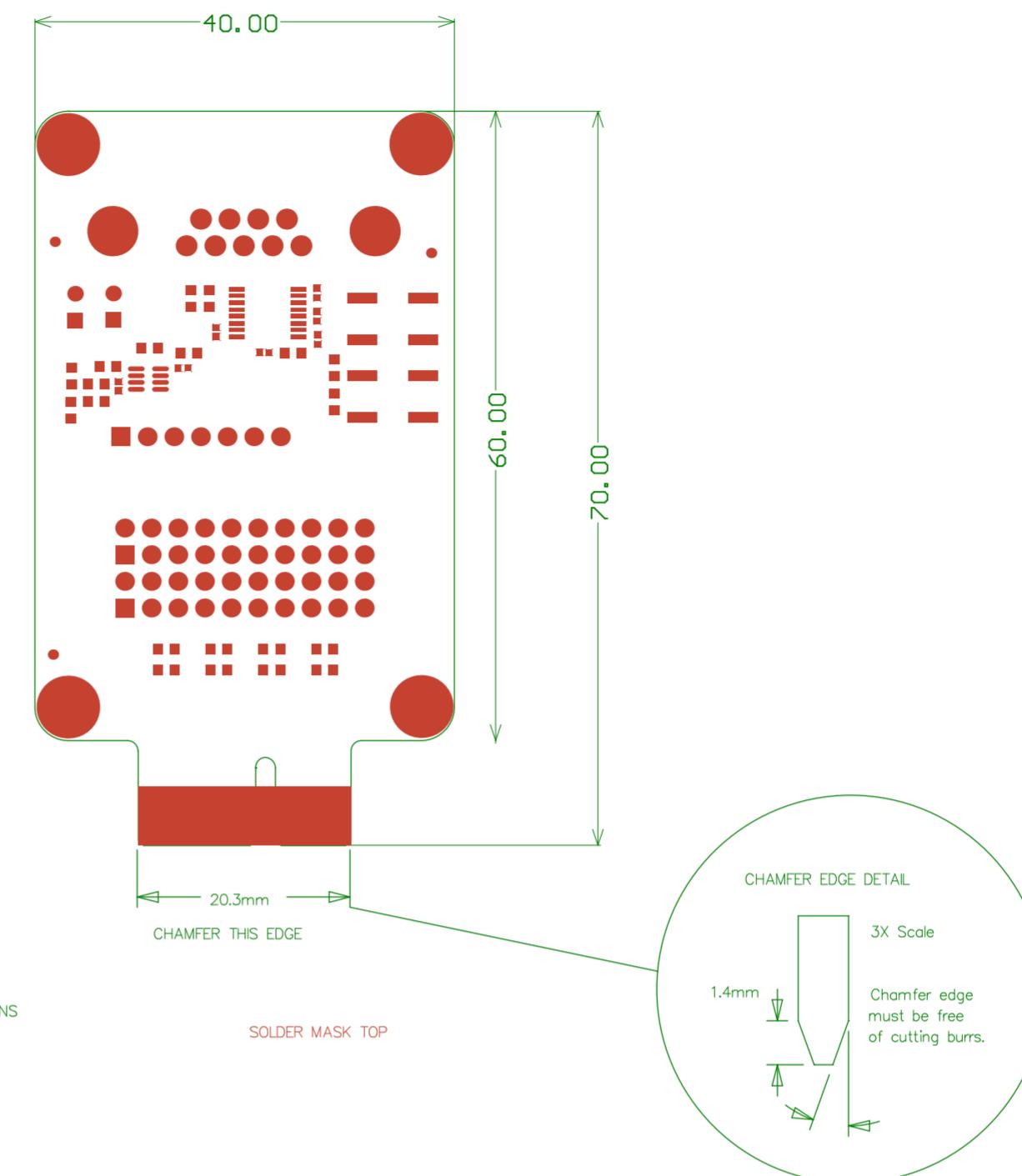
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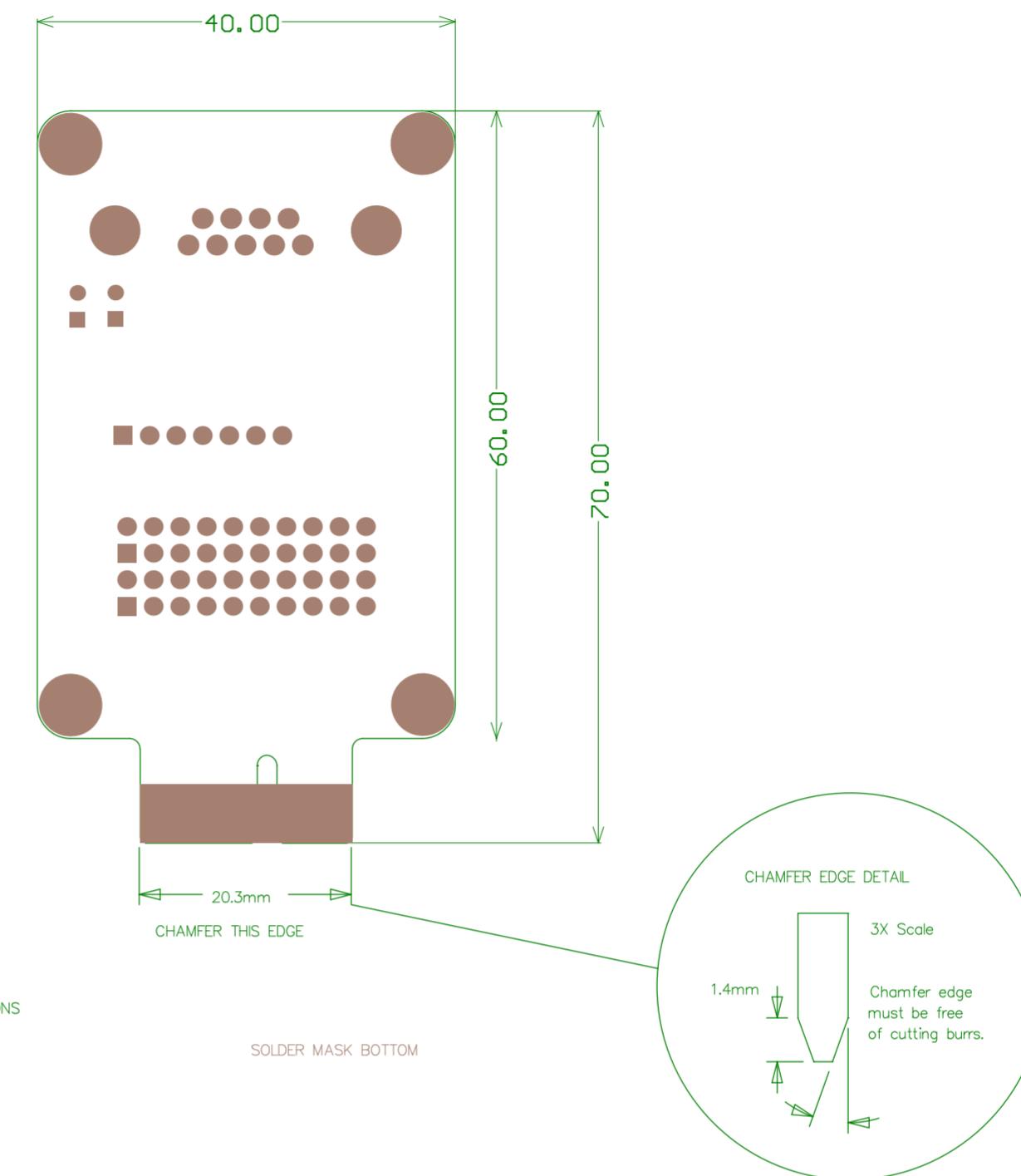
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FABRICATION INSTRUCTIONS

SOLDER MASK BOTTOM

CHAMFER THIS EDGE

20.3mm

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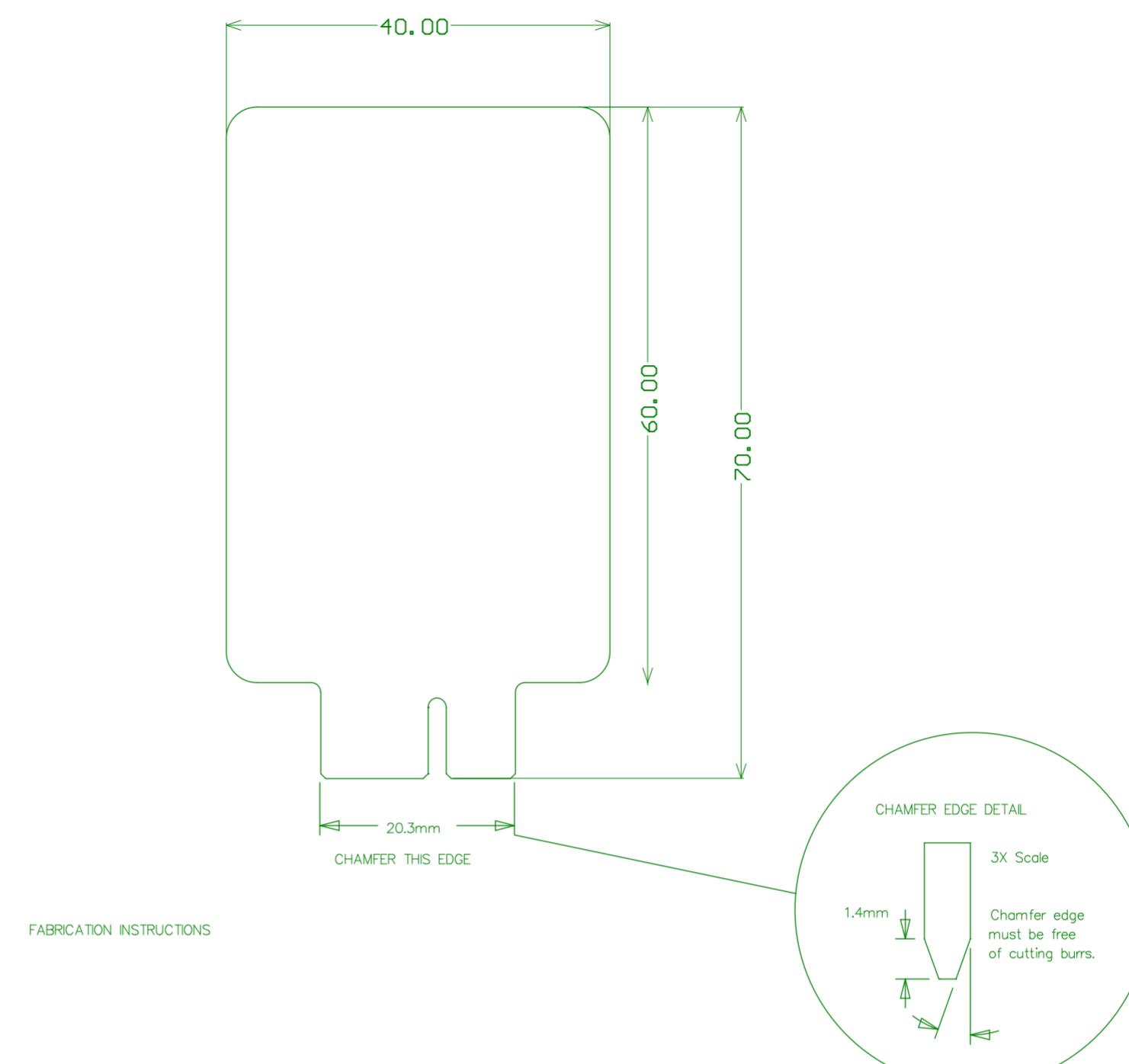
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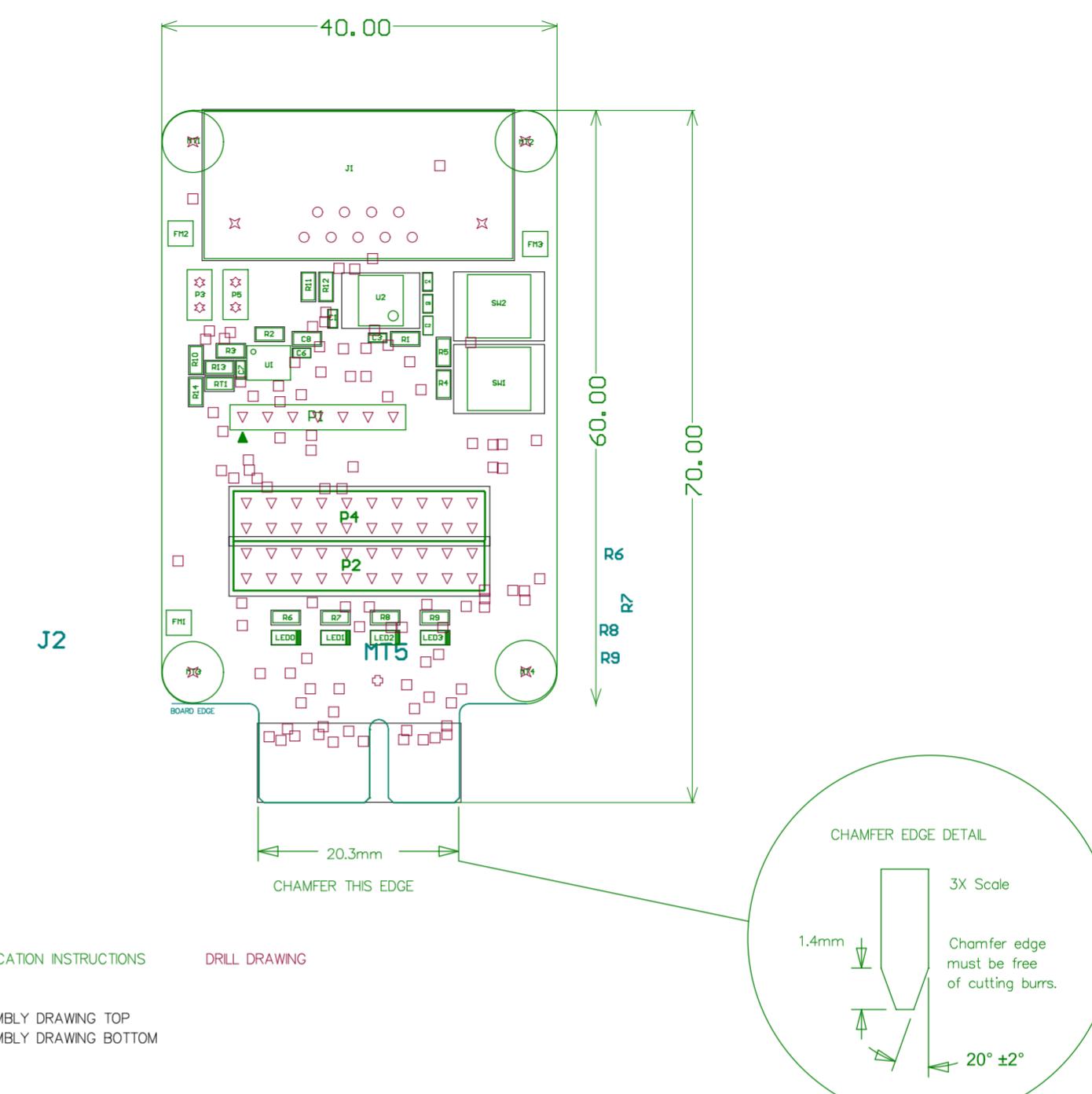
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Symbol	Hit Count	Tool Size	Plated	Hole Type
□	98	0.3mm (11.811mil)	PTH	Round
◊	4	0.9mm (35.433mil)	PTH	Round
▽	47	1mm (39.37mil)	PTH	Round
○	9	1.2mm (47.244mil)	PTH	Round
◊	1	2.8mm (110.236mil)	NPTH	Round
◊	6	3.2mm (125.984mil)	PTH	Round
<b>165 Total</b>				

**Drill Drawing.**



PCB Manufacturing Notes

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Minimum Track & Gap - 0.15mm  
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## Impedance Control

Not required

## Copper Thieving/Balancing

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Finish

#### A.) Conductive finish

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- B.) Soldermask

## Liquid photo in Supplier show

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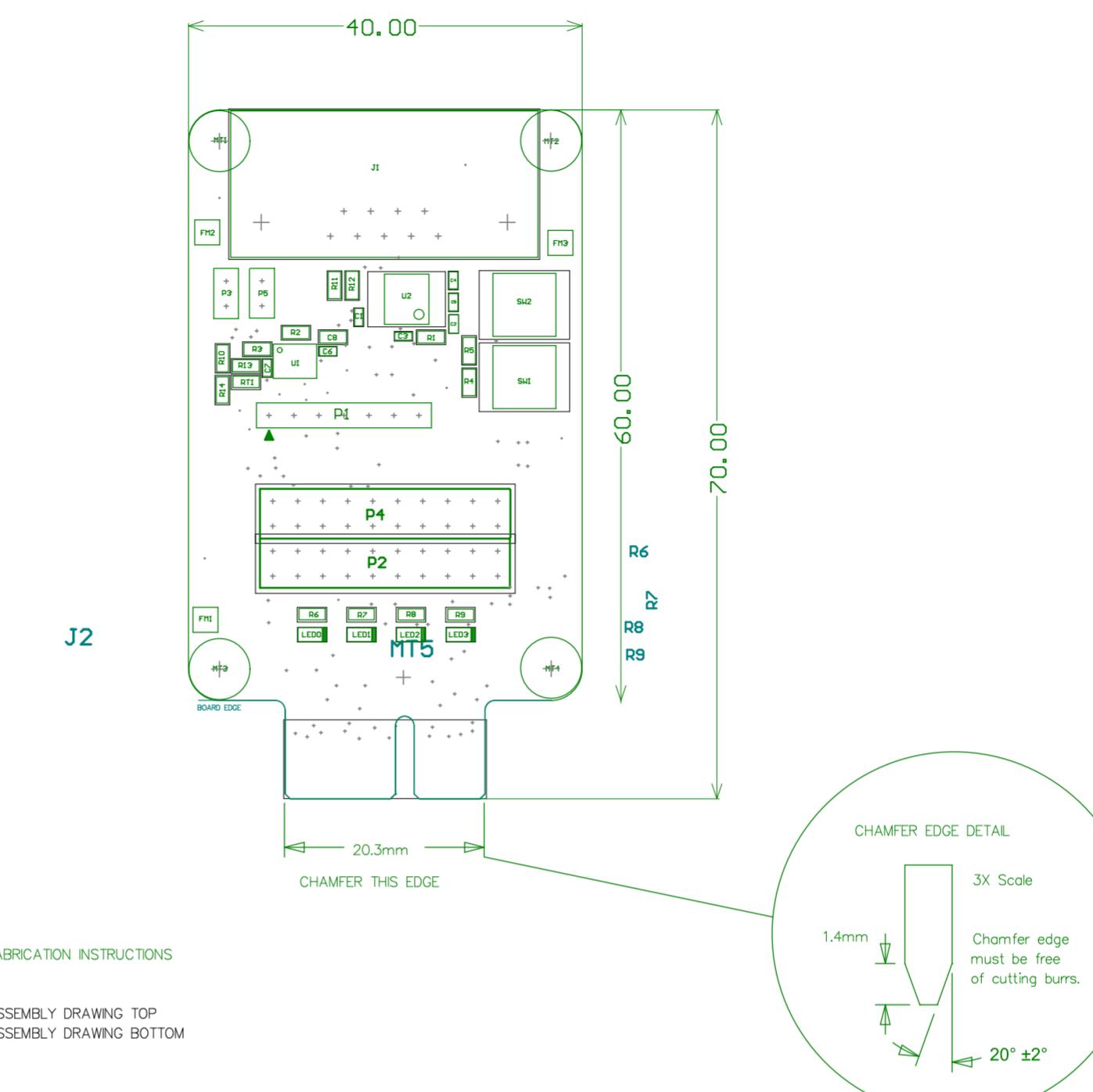
C.) Silkscreen

Colour white. S

## Drill Data

## Drill data

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# BOM

XA-SK-GPIO

Source Data From:

XIPCB-002-GPIO.PjPcb

Project:

XIPCB-002-GPIO.PjPcb

Variant:

None



Report Date: 20/12/2012 11:45:49  
Print Date: 20-Dec-12 11:45:53 AM

#	LibRef	Designator	Description	Quantity
1	E-01-0001	R10	RES 1k 0603 1%	1
2	E-01-0002	R1, R4, R5	RES 10k 0603 1%	3
3	E-01-0010	R11, R12	RES 330R 0603 1%	2
4	E-01-0021	R2, R3	RES 4.7k 0603 1%	2
5	E-01-0022	R6, R7, R8, R9, R13	RES 470R 0603 1%	5
6	E-01-0122	R14	RES 33k 0603 1%	1
7	E-02-0002	C1, C2, C3, C4, C5, C6	MLCC 100nF 0402 X7R 16V	6
8	E-02-0006	C8	MLCC 10uF 0603 X5R 6.3V	1
9	E-02-0061	C7	MLCC 1nF 0402 X7R 50V	1
10	E-04-0071	J1	D-Subminiature Connector, 9 pin, Male, Right Angle, US Footprint, with screw locks	1
11	E-12-0001	LED0, LED1, LED2, LED3	LED, GREEN, 0603	4
12	E-13-0118	U1	ADC, 10BIT, 4 Channel, I2C, SOT23-8	1
13	E-13-0119	U2	RS232 1 Tx/1 Rx, With Charge Pump, ESD Protected, 250kbps, 3V-5.5V, TSSOP-16	1
14	E-16-0003	SW1, SW2	Tactile Switch, Momentary, SMD, J Bend	2
15	E-18-0009	RT1	Thermistor, 1K, NTC, 0603, SMD	1
16	P-01-0011	PROD1, PROD2, PROD3, PROD4	Feet, Nylon, M3, 6mm Standoff	4
Approved		Notes		36